

**CLEAN VERSION OF SPECIFICATION PARAGRAPH  
BEGINNING ON PAGE 11, LINE 13, ENDING ON PAGE 11, LINE 20**



**METHOD FOR ATTACHING A SEMICONDUCTOR DIE TO A SUBSTRATE**

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The substrate 12 is placed on an automated conveyor system with the first side 24 facing downwardly. The automated machinery then indexes the substrate 12 to a tape punch station. As shown in Figure 5a, the tape 40 is punched into two strips and the first side 42 is pressed against the die attach area 26 of the substrate 12. The tape 40 is heated momentarily to complete the lamination process. The heat applied is generally below that required to crosslink or set the adhesive. In one embodiment, pressure and 100 deg C heat are applied for 100 ms.

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